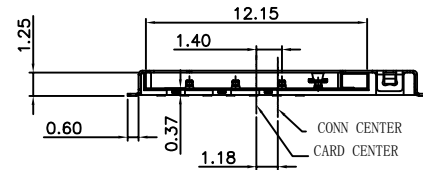
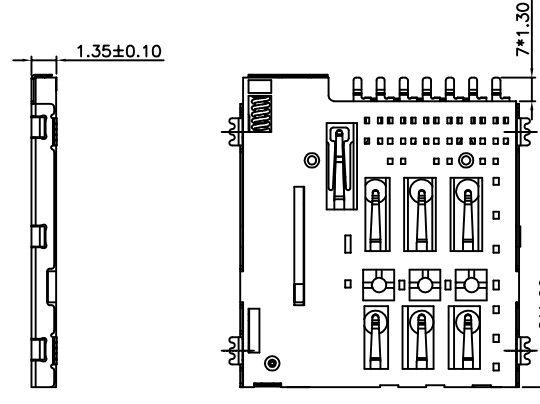
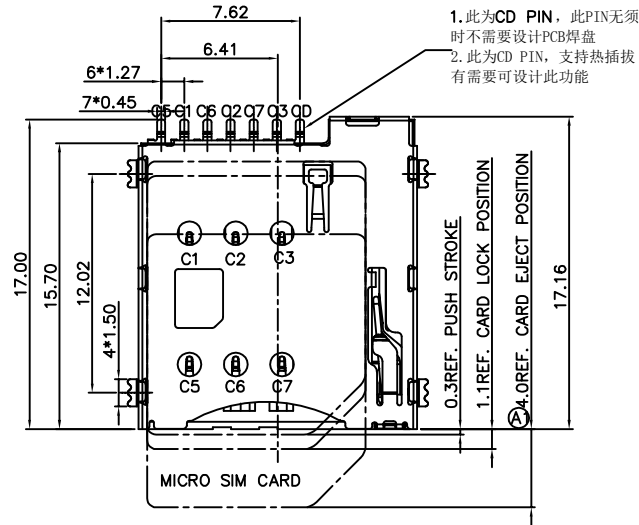
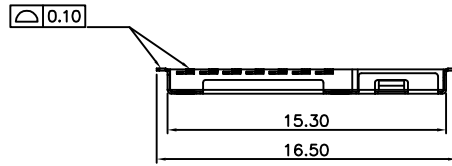
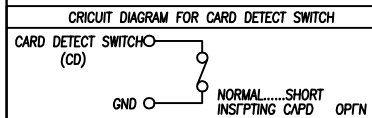
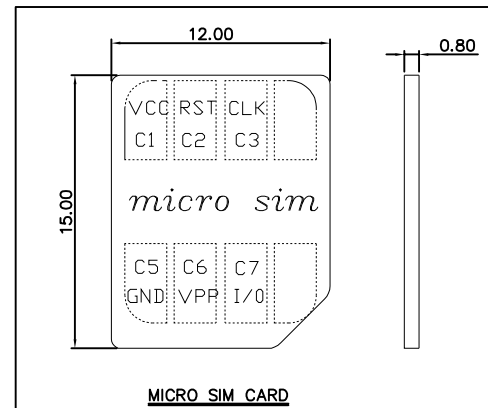
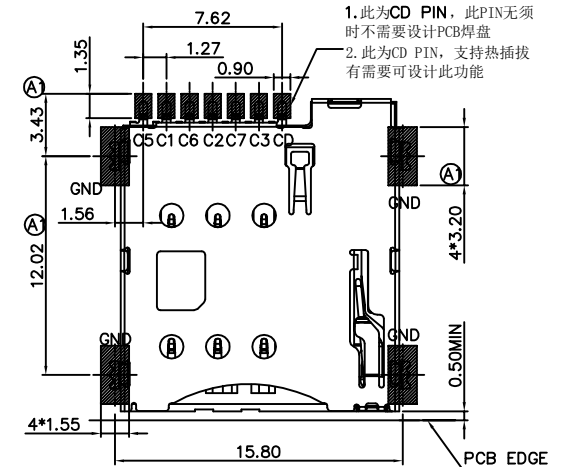


REV	DATE	ECN NO.	MODIFICATION	APPROVER
A	2016/10/14		NEW	Jason_Lee
A1	2017/05/15	RD00317051501	SIZE CHANGE	Jason_Lee

NOTES:
MATERIAL:
Housing: High Temperature thermoplastic, UL94V-0
Terminal: Copper Alloy
Tin 100u" at Solder Tail,
Selected Gold 1u" on Contact Area Plating.
Shell: Stainless
Nickel plating bottom 50~80u" soldering foot gold flash
SPECIALITY:
Rated Current: 0.5A MAX
Rated Voltage: 50V
Ambient Temperature Range: -20°C~+60°C
storage Temperature Range: -40°C~+70°C
Ambient Humidity Range: 95% R.H. Max.
Contact Resistance: 100mΩ Max
Insulation Resistance: 1000MΩ/250V DC
Dielectric Withstanding Voltage: 500V AC
Durability: 5000 cycles
Temperature 260±5°C,



IM pin Assignment	
IN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



GENERAL TOLERANCE		UNITS	NAME:	ATOM® 深圳市爱特姆科技有限公司 SHENZHEN ATOM TECHNOLOGY CO., LTD.	
SELECT		mm	MICRO SIM CARD 6P PUSH PUSH	PART NO:	TITLE: MICRO SIM CARD 6P PUSH PUSH SMT H=1.35mm 带检测脚 无柱
TOL.	1 2 3	MAT'L	SI62C-01200	APPD:	DWG NO. ATOM-A03337
ON.		FINISH	CHKD:	DR:	SCALE SHEET REV
X.XXX	±0.10±0.05±0.15	Q'TY	JACK	1:1	1/1 A1
X.XX	±0.15±0.13±0.25				
X.X	±0.20±0.25±0.5				
X.	±0.30±0.36±1.00				
ANGLE	±2'				